

4-Quadrant Silicon PIN Photodiode



FEATURES

• Package type: surface-mount

• Technology: epitaxial

- Package form: top view
- Dimensions (L x W x H in mm): 4.72 x 4.72 x 0.8
- AEC-Q101 qualified
- · High photo sensitivity
- Floor life: 168 h, MSL 3, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912







ROHS COMPLIANT HALOGEN FREE GREEN (5-2008)

DESCRIPTION

K857PE is a 4-quadrant photo detector in surface-mount package. Each quadrant PD has an active area of 1.6 mm².

LINKS TO ADDITIONAL RESOURCES





PRODUCT SUMMARY				
COMPONENT	I_{ra} (μA) (E _e = 1.0 mW/cm ² , λ = 850 nm, V_R = 5 V)	φ (°)	λ _{0.1} (nm)	
K857PE	8.5	± 60	690 to 1050	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
K857PE	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Top view		
K857PE-GS15	Tape and reel	MOQ: 5000 pcs, 5000 pcs/reel	Top view		

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	20	V
Operating temperature range		T _{amb}	-40 to +110	°C
Storage temperature range		T _{stg}	-40 to +110	°C
Soldering temperature	According to reflow solder profile Fig. 8	T _{sd}	260	°C
ESD safety HBM	± 2000 V, 1.5 kΩ, 100 pF, 3 pulses	ESD _{HBM}	2.0	kV



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BASIC CHARACTERISTICS, SINGLE QUADRANT (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F	-	0.9	1.3	V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}	-	1	10	nA
Diode capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0$	C _D	-	11	-	pF
	V _R = 3 V, f = 1 MHz, E = 0	C _D	-	7	-	pF
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 850 \text{ nm}$	I _k	-	8.5	-	μA
Temperature coefficient of Ira	$E_e = 1 \text{ mW/cm}^2, V_R = 5 \text{ V}$	TK _{lra}	-	0.15	-	%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 850 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	7	8.5	11	μΑ
	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 940 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	-	5.7	-	μA
Angle of half sensitivity		φ	-	± 60	-	0
Wavelength of peak sensitivity		λ_{p}	-	840	-	nm
Range of spectral bandwidth		λ _{0.1}	-	690 to 1050	-	nm
Rise time	$V_R = 10 \text{ V}, R_L = 50 \Omega, \lambda = 830 \text{ nm}$	t _r	-	30	-	ns
Fall time	V_R = 10 V, R_L = 50 Ω , λ = 830 nm	t _f	-	30	-	ns

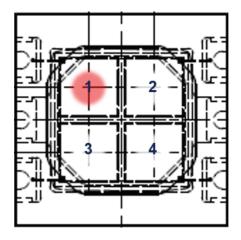
BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

Values per quadrant q (q = 1, 2, 3, 4)

CROSS-		

Laser illumination (850 nm, 65 μ m spot diameter, radiant power 0.7 mW) of center of PD quadrant 1 (q = 1), $V_{R, q}$ = 5 V applied to all quadrants (q = 1, 2, 3, 4)

(4 ') = ' - ' ')			_
ILLUMINATED	MEASURED PARAMETER	TYP. VALUE	UNIT
Yes	Ira_850_1	100	%
No	lra_850_2	0.1	%
No	Ira_850_3	0.1	%
No	lra_850_4	0.05	%



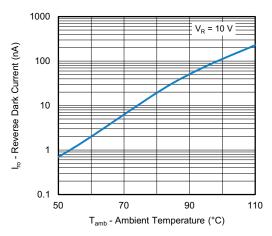
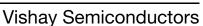


Fig. 1 - Reverse Dark Current vs. Ambient Temperature





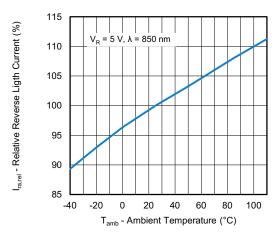


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

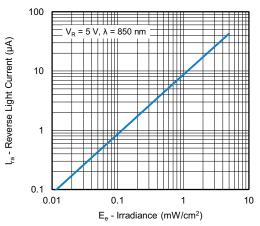


Fig. 3 - Reverse Light Current vs. Irradiance

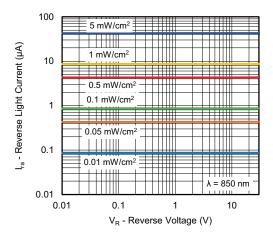


Fig. 4 - Reverse Light Current vs. Reverse Voltage

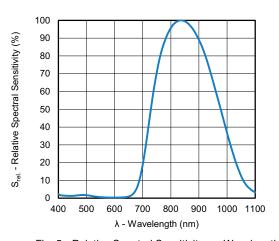


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

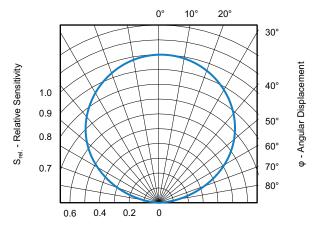
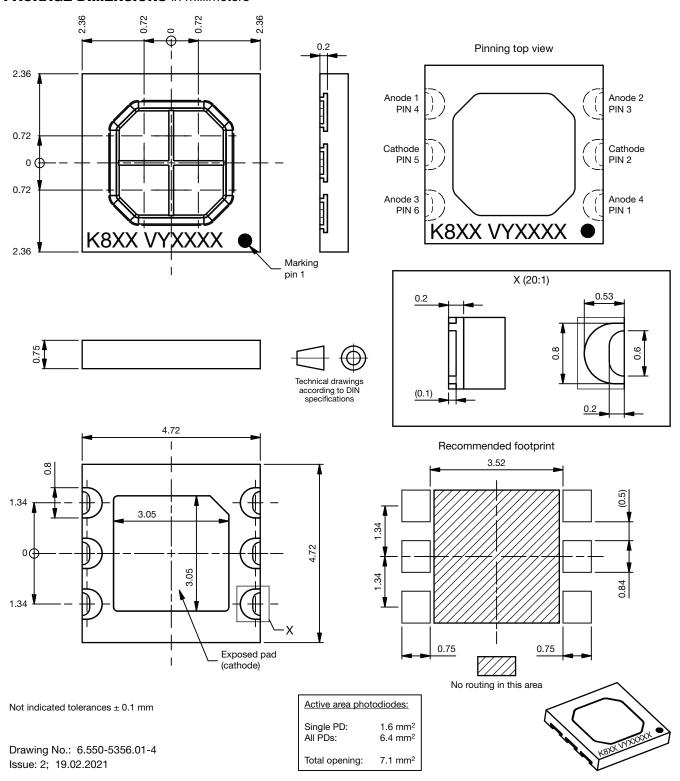


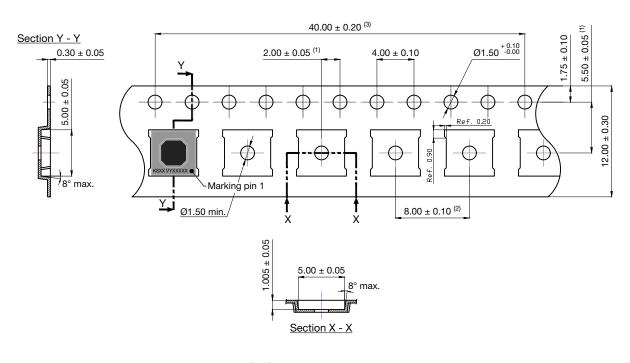
Fig. 6 - Relative Sensitivity vs. Angular Displacement

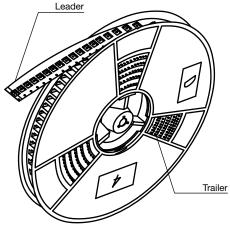


PACKAGE DIMENSIONS in millimeters



TAPE AND REEL DIMENSIONS in millimeters





Notes

- Allowable camber to be 1 mm per 250 mm in length for single winding and 2 mm per 250 mm in length for cross winding
- (1) Measure from centerline of sprocket hole to centerline of pocket
- (2) Measure from centerline of pocket to centerline of pocket
- $^{(3)}$ Pitch tolerance for sprocket hole, 10 pitch cumulative tolerance is \pm 0.2 mm



SOLDER PROFILE

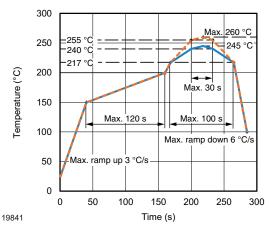


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %



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